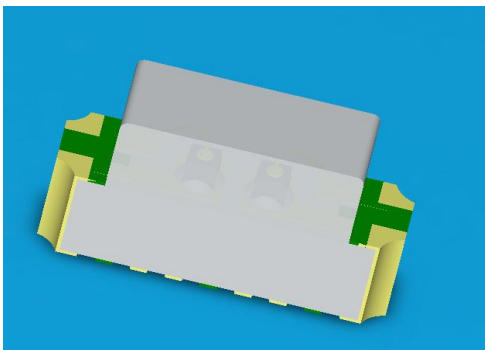


SMD ■ B EASV2010RWA0



Features

- Package in 8mm tape on 7" diameter reel.
- Compatible with automatic placement equipment.
- Compatible with infrared and vapor phase reflow solder process.
- Mono-color type.
- Pb-free.
- The product itself will remain within RoHS compliant version.
- Compliance with EU REACH
- Compliance Halogen Free .(Br <900 ppm ,Cl <900 ppm , Br+Cl < 1500 ppm).

Description

- The SMD LED is much smaller than lead frame type components, thus enable smaller board size, higher packing density, reduced storage space and finally smaller equipment to be obtained.
- Besides, lightweight makes them ideal for miniature applications. etc.

Applications

- Backlighting in dashboard and switch.
- Telecommunication: indicator and backlighting in telephone and fax.
- Flat backlight for LCD, switch and symbol.
- General use.

Device Selection Guide

Chip Type	Chip Materials	Emitted Color	Resin Color
R6	AlGaInP	Brilliant Red	Yellow Diffused
T1	InGaN	Pure White	Yellow Diffused

Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit
Reverse Voltage	V_R	5	V
Forward Current	I_F	R6 : 25 T1 : 10	mA
Peak Forward Current (Duty 1/10 @1KHz)	I_{FP}	R6 : 60 T1 : 100	mA
Power Dissipation	P_d	R6 : 95 T1 : 40	mW
Operating Temperature	T_{opr}	-40 ~ +85	°C
Storage Temperature	T_{stg}	-40 ~ +90	°C
Electrostatic Discharge	ESD_{HBM}	R6 : 2000 T1 : 150	V
Soldering Temperature	T_{sol}	Reflow Soldering : 260 °C for 10 sec. Hand Soldering : 350 °C for 3 sec.	

Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Luminous Intensity	I_v	R6 : 18.0 T1 : 45.0	-----	45.0 112.0	mcd	$I_F = 5mA$
Viewing Angle	$2\theta_{1/2}$	-----	140	-----	deg	
Peak Wavelength	λ_p	R6 : -----	632.0	-----	nm	
Dominant Wavelength	λ_d	R6 : 617.5	-----	629.5	nm	
Spectrum Radiation Bandwidth	$\Delta\lambda$	R6 : -----	20	-----	nm	
Forward Voltage	V_F	R6 : 1.55. T1 : 2.50	-----	2.15 3.10	V	$V_R = 5V$
Reverse Current	I_R	R6 : ----- T1 : -----	-----	10 50	μA	

Note:

1. Tolerance of Luminous Intensity: ±11%
2. Tolerance of Dominant Wavelength: ±1nm
3. Tolerance of Forward Voltage ±0.1V

Bin Range of Luminous Intensity

R6

Bin Code	Min.	Max.	Unit	Condition
M1	18.0	22.5	mcd	$I_F = 5\text{mA}$
M2	22.5	28.5		
N1	28.5	36.0		
N2	36.0	45.0		

Bin Range of Luminous Intensity

T1

Bin Code	Min.	Max.	Unit	Condition
P1	45.0	57.0	mcd	$I_F = 5\text{mA}$
P2	57.0	72.0		
Q1	72.0	90.0		
Q2	90.0	112.0		

Bin Range Of Dom. Wavelength

R6

Bin Code	Min.	Max.	Unit	Condition
E4	617.5	621.5	nm	$I_F = 5\text{mA}$
E5	621.5	625.5		
E6	625.5	629.5		

Bin Range Of Forward Voltage

R6

Bin Code	Min.	Max.	Unit	Condition
00	1.55	1.75	V	$I_F = 5\text{mA}$
0	1.75	1.95		
1	1.95	2.15		

Bin Range Of Forward Voltage

T1

Bin Code	Min.	Max.	Unit	Condition
9	2.50	2.70	V	$I_F = 5\text{mA}$
10	2.70	2.90		
11	2.90	3.10		

Note:

1. Tolerance of Luminous Intensity: $\pm 11\%$
2. Tolerance of Dominant Wavelength: $\pm 1\text{nm}$
3. Tolerance of Forward Voltage $\pm 0.1\text{V}$

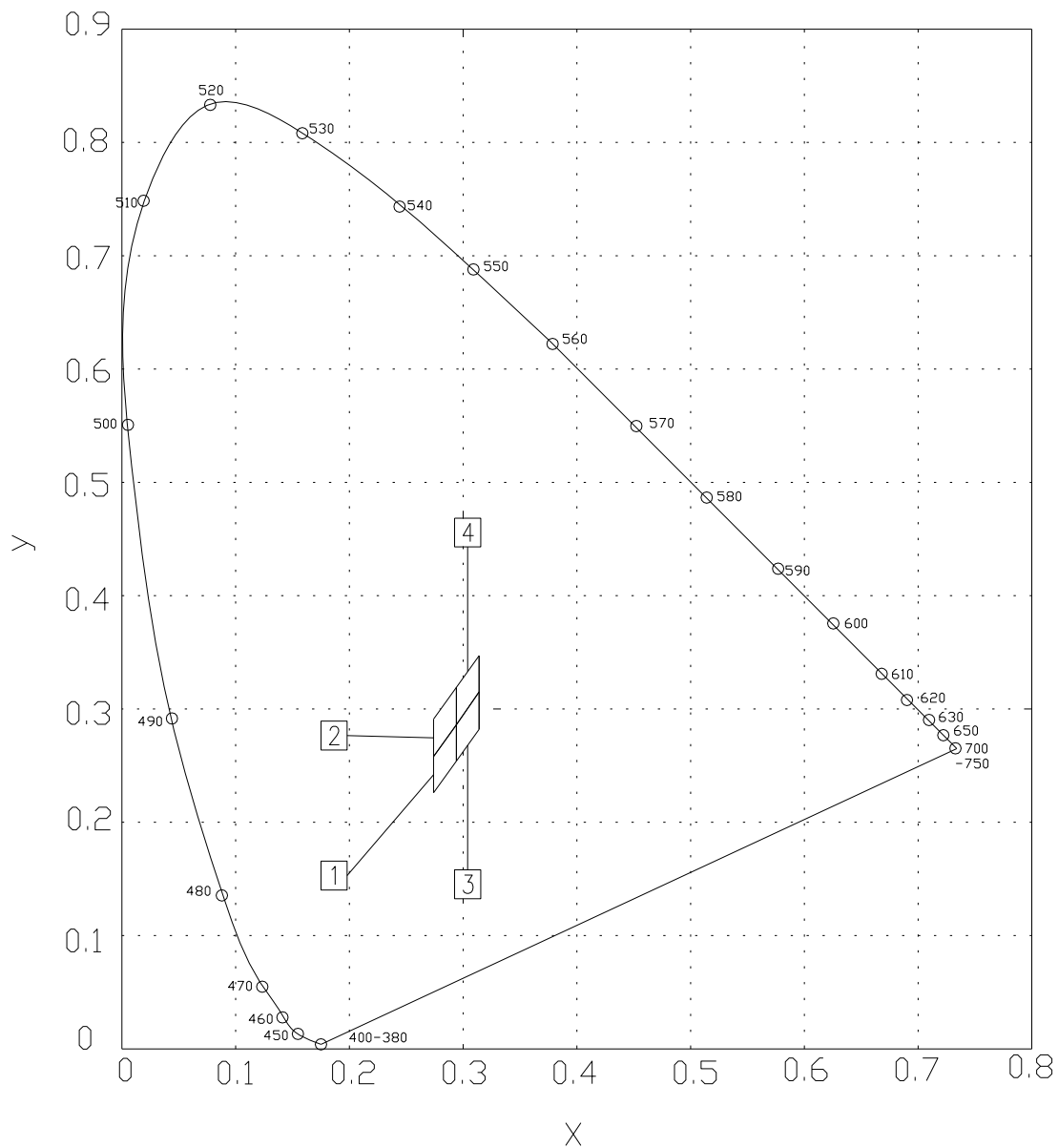
Chromaticity Coordinates Specifications for Bin Grading

Bin Code	CIE_x	CIE_y	Condition
1	0.274	0.226	I _F =5mA
	0.274	0.258	
	0.294	0.286	
	0.294	0.254	
2	0.274	0.258	
	0.274	0.291	
	0.294	0.319	
	0.294	0.286	
3	0.294	0.254	
	0.294	0.286	
	0.314	0.315	
	0.314	0.282	
4	0.294	0.286	
	0.294	0.319	
	0.314	0.347	
	0.314	0.315	

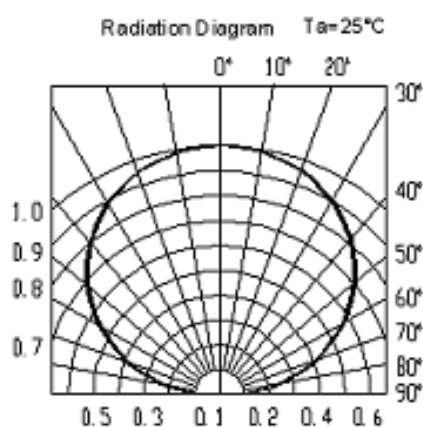
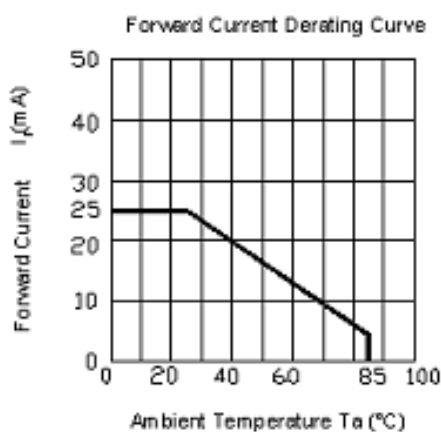
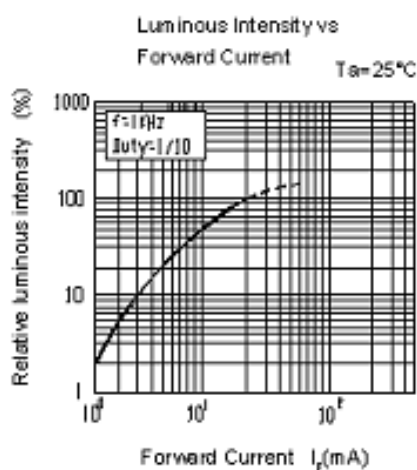
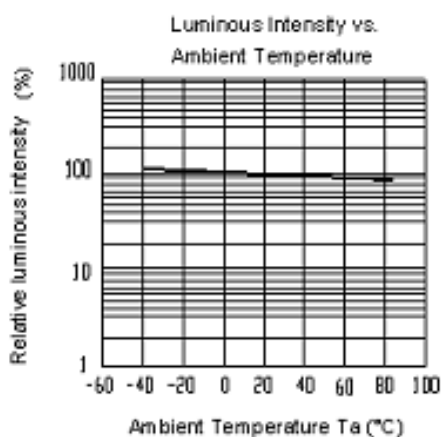
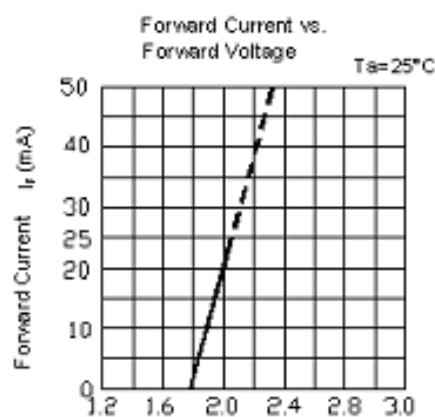
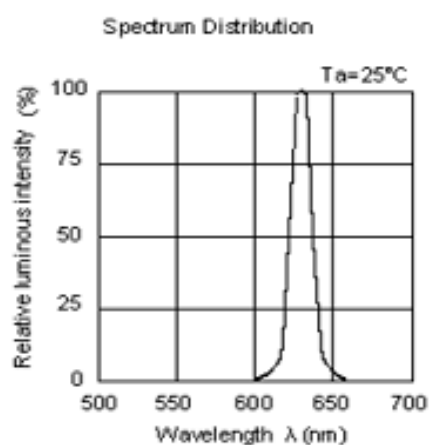
Notes:

- 1.The C.I.E. 1931 chromaticity diagram (Tolerance ± 0.01).
- 2.The products are sensitive to static electricity and care must be fully taken when handling products.

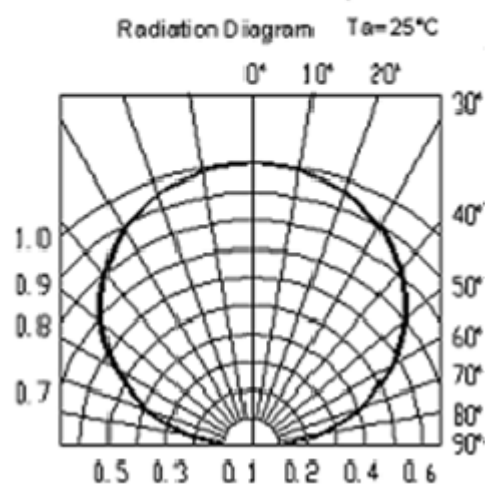
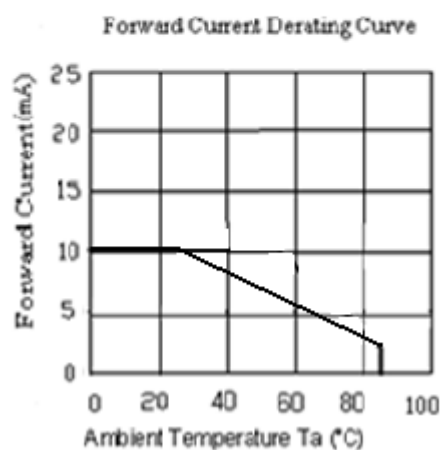
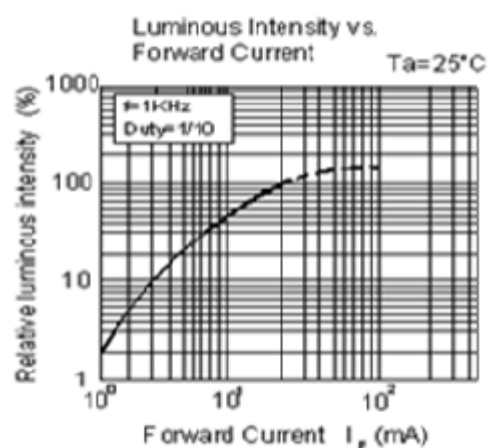
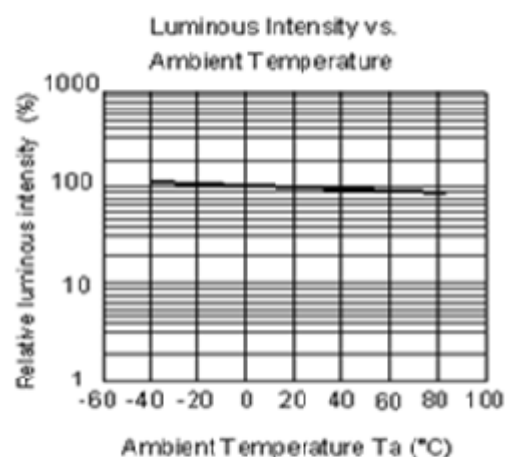
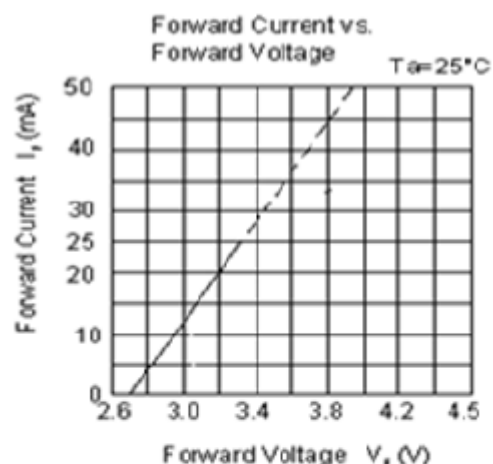
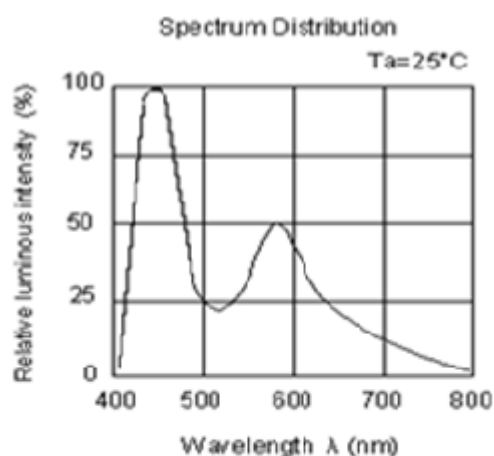
CIE Chromaticity Diagram



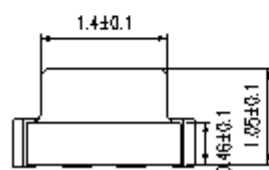
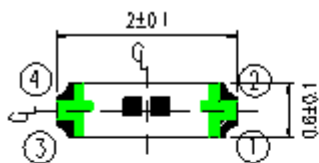
Typical Electro-Optical Characteristics Curves R6



Typical Electro-Optical Characteristics Curves T1



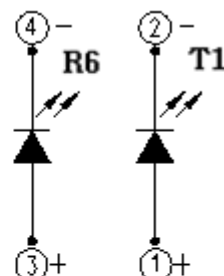
Package Outline Dimensions



Side

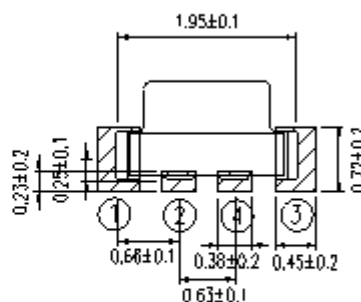


Bottom



Polarity

Recommend Soldering Pad



Suggested pad dimension is just for reference only.
Please modify the pad dimension based on individual need.

Note: Tolerances unless mentioned ± 0.1 mm. Unit = mm

Label Explanation



5

CPN: XXXXXXXXXXXXXXXXXXXX 測試區



XXXXXXXXXX-XXXXXXXXXX-XXXXXXXXXX-XXXXXXXXXX

P/N: XXXXXXXXXXXX



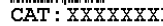
XXXXXXXXXX-XXXXXXXXXX-XXXXXXXXXX-XXXXXXXXXX

LOT NO: Y150716XXX-XXXXXXXXXX-XXXXXXXXXX

QTY: 0123456789 HUE: XXXXXXXXXXXX



CAT: XXXXXXXXXXXX REF: XXXXXXXXXXXX



REFERENCE: BTPYYMDDXXXXX



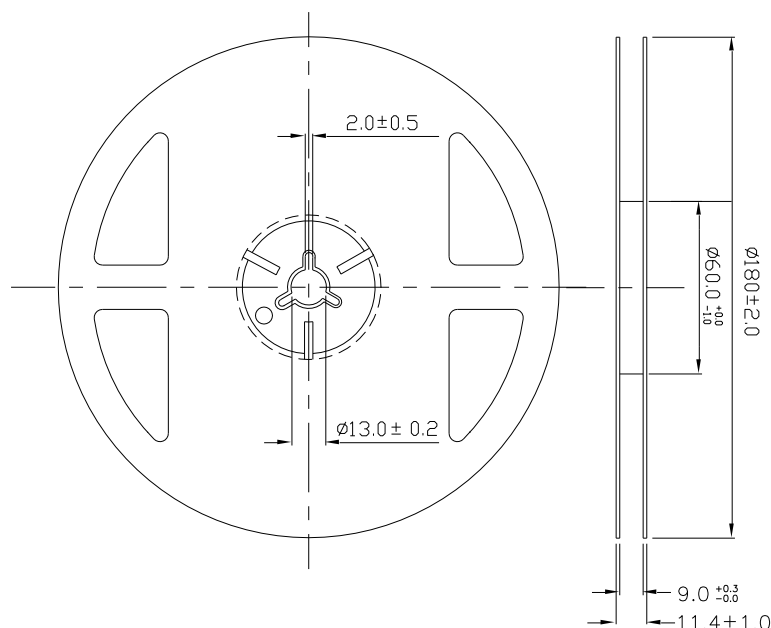
MSL-X

MADE IN TAIWAN



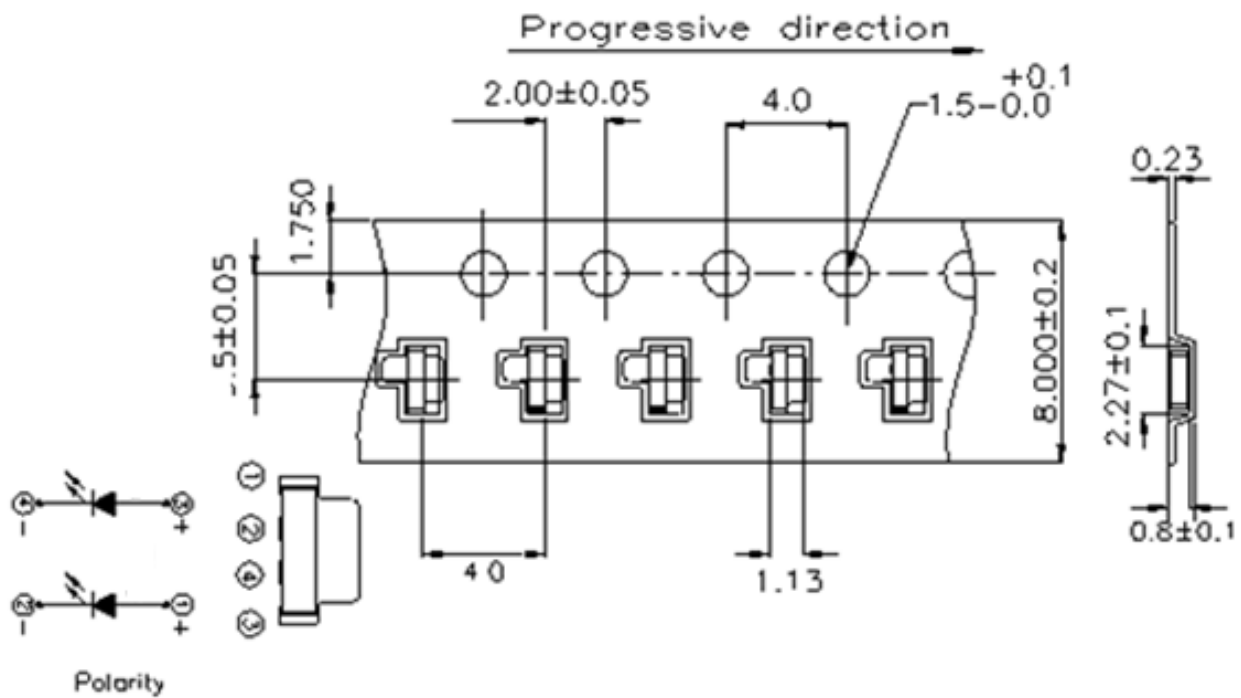
- CPN: Customer's Product Number
- P/N: Product Number
- QTY: Packing Quantity
- CAT: Luminous Intensity Rank
- HUE: Chromaticity Coordinates & Dom. Wavelength Rank
- REF: Forward Voltage Rank
- LOT No: Lot Number

Reel Dimensions



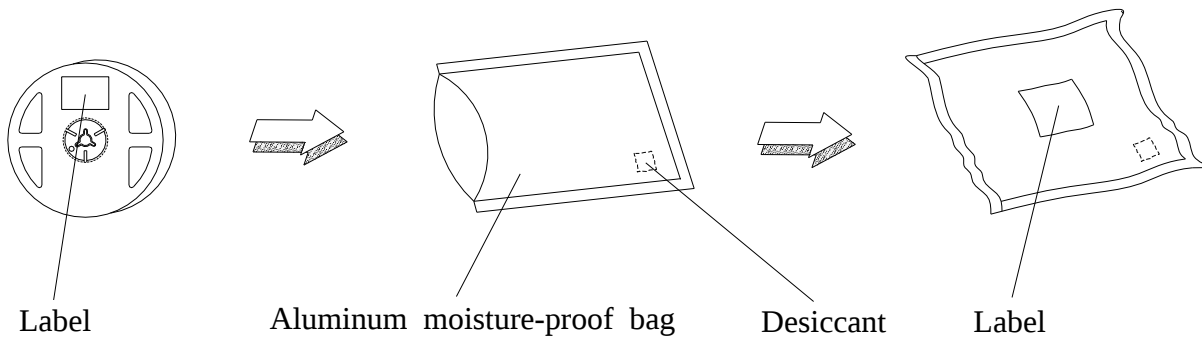
Note: The tolerances unless mentioned is $\pm 0.1\text{mm}$, Unit = mm

Carrier Tape Dimensions: Loaded quantity 3000 PCS per reel



Note: The tolerances unless mentioned is $\pm 0.1\text{mm}$,Unit = mm

Moisture Resistant Packaging



Precautions For Use

1. Over-current-proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage

2.1 Do not open moisture proof bag before the products are ready to use.

2.2 Before opening the package: The LEDs should be kept at 30°C or less and 90%RH or less.

2.3 After opening the package :The LED's floor life is 1 year under 30°C or less and 60%RH or less.

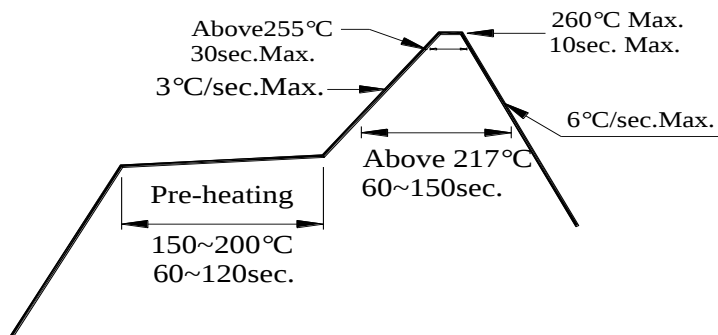
If unused LEDs remain, it should be stored in moisture proof packages.

2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment : 60±5°C for 24 hours.

3. Soldering Condition

3.1 Pb-free solder temperature profile



3.2 Reflow soldering should not be done more than two times.

3.3 When soldering, do not put stress on the LEDs during heating.

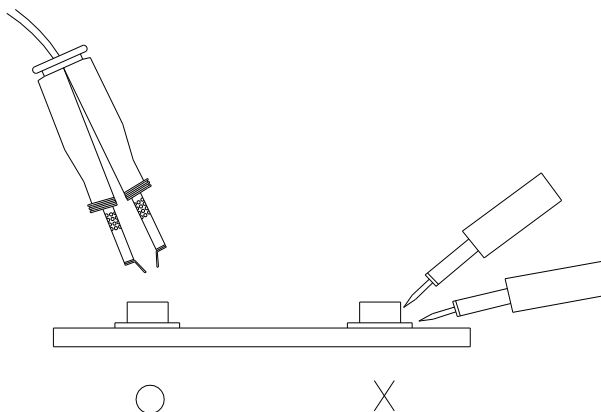
3.4 After soldering, do not warp the circuit board.

4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



Application Restrictions

High reliability applications such as military/aerospace, automotive safety/security systems, and medical equipment may require different product. If you have any concerns, please contact everlightamericas before using this product in your application. This specification guarantees the quality and performance of the product as an individual component. Do not use this product beyond the specification described in this document.